## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

Vassoudevane Lebonheur et al.

Title:

MOLD COMPOUND CAP IN A FLIP CHIP MULTI-MATRIX ARRAY PACKAGE AND

PROCESS OF MAKING SAME

Docket No.:

884.862US1

Filed:

June 30, 2003

Examiner:

Victor A Mandala

DEC 1 9 2005

Serial No.: 10/612,764

Due Date: February 17, 2006

Group Art Unit: 2826

## **MS** Amendment

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

We are transmitting herewith the following attached items (as indicated with an "X"):

 $\underline{X}$  Return postcard.

X Response Under 37 CFR 1.111 (15 pgs.).

If not provided for in a separate paper filed herewith, Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

Customer Number 21186

Atty: Ann M. McCrackin

Reg. No. 42,858

<u>CERTIFICATE UNDER 37 CFR 1.8:</u> The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: MS Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this <u>1440</u> day of December, 2005.

Amy Moriarty

Name

Signature

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

(GENERAL)

S/N 10/612,764

DEC 1. 9 2005 \_\_\_\_

## IN THE UNITED STATES ATENT AND TRADEMARK OFFICE

Applicant: Vassoudevane Lebonheur et al. Examiner: Victor A Mandala

Serial No.: 10/612,764 Group Art Unit: 2826 Filed: June 30, 2003 Docket No.: 884.862US1

Title: MOLD COMPOUND CAP IN A FLIP CHIP

MULTI-MATRIX ARRAY PACKAGE AND PROCESS

OF MAKING SAME

Assignee: Intel Corporation Customer Number: 21186

## RESPONSE UNDER 37 CFR § 1.111

MS Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

This responds to the Office Action mailed on November 17, 2005. Please consider the remarks concerning the above-identified patent application as follows.

**PATENT**